

• General Description

The AGM016T08LL combines advanced trench MOSFET technology with a low resistance package to provide extremely low $R_{DS(ON)}$.

This device is ideal for load switch and battery protection applications.

Features

- Advance high cell density Trench technology
- Low R_{DS(ON)} to minimize conductive loss
- Low Gate Charge for fast switching
- Low Thermal resistance
- 100% Avalanche tested
- 100% DVDS tested

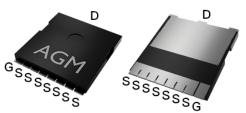
Application

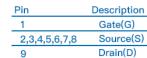
- MB/VGA Vcore
- SMPS 2nd Synchronous Rectifier
- POL application
- BLDC Motor driver

Product Summary

BVDSS	RDSON	ID
85V	1.38mΩ	280A

TOLL Pin Configuration





Top	View
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Bottom View

Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
AGM016T08LL	AGM016T08LL	TOLL	330mm	25mm	2000

Table 1. Absolute Maximum Ratings (TA=25℃)

Symbol	Parameter	Value	Unit
VDS	Drain-Source Voltage (VGS=0V)	85	V
VGS	Gate-Source Voltage (VDS=0V)	±20	V
ID	Drain Current-Continuous(Tc=25℃) (Note 1)	280	А
_	Drain Current-Continuous(Tc=100℃)	231	А
IDM (pluse)	Drain Current-Pulsed (Note 2)	1120	А
PD	Maximum Power Dissipation(Tc=25 ℃)	258	W
	Maximum Power Dissipation(Tc=100℃)	129	w
EAS	Avalanche energy (Note 3)	1521	mJ
TJ,TSTG	Operating Junction and Storage Temperature Range	-55 To 175	$^{\circ}$

Table 2. Thermal Characteristic

Symbol	Parameter	Тур	Max	Unit
RθJA	Thermal Resistance Junction-ambient (Steady State) ¹		42	°C/W
RθJC	Thermal Resistance Junction-Case ¹		0.58	°C/W



Table 3. Electrical Characteristics (TJ=25°C unless otherwise noted)

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
On/Off Sta	ates					
BVDSS	Drain-Source Breakdown Voltage	VGS=0V ID=250µA	85			V
IDSS	Zero Gate Voltage Drain Current	VDS=85V,VGS=0V			1	μA
IGSS	Gate-Body Leakage Current	VGS=±20V,VDS=0V			±100	nA
VGS(th)	Gate Threshold Voltage	VDS=VGS,ID=250μA	2.2	2.6	3.3	V
gFS	Forward Transconductance	VDS=5V,ID=10A		34		S
RDS(on)	Drain-Source On-State Resistance	VGS=10V, ID=50A		1.38	1.8	mΩ
Dynamic (Characteristics					
Ciss	Input Capacitance			5545		pF
Coss	Output Capacitance	VDS=40V,VGS=0V, F=1MHZ		2096		pF
Crss	Reverse Transfer Capacitance			161		pF
Rg	Gate resistance	VGS=0V, VDS=0V,f=1.0MHz		1.2		Ω
Switching	Times					
td(on)	Turn-on Delay Time			28	1	nS
tr	Turn-on Rise Time	VGS=10V,VDS=42V,		74	-	nS
td(off)	Turn-Off Delay Time	ID=50A,RGEN=4.5Ω		86		nS
tf	Turn-Off Fall Time			33		nS
Qg	Total Gate Charge			140		nC
Qgs	Gate-Source Charge	VGS=10V, VDS=42V, ID=50A		56		nC
Qgd	Gate-Drain Charge			26		nC
Source-Di	rain Diode Characteristics					
ISD	Source-Drain Current(Body Diode)				280	А
VSD	Forward on Voltage	VGS=0V,IS=50A			1.2	V
trr	Reverse Recovery Time	IF=50A , dI/dt=100A/μs ,		115		ns
Qrr	Reverse Recovery Charge	TJ=25℃		320		nc

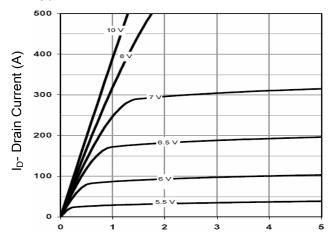
Notes 1.The maximum current rating is package limited.

Notes 2.Repetitive Rating: Pulse width limited by maximum junction temperature

Notes 3.EAS condition: TJ=25 $^{\circ}$ C,VDD=40V,Vgs=10V,ID=78A,L=0.5mH,RG=25ohm



Typical Electrical and Thermal Characteristics



Vds Drain-Source Voltage (V)



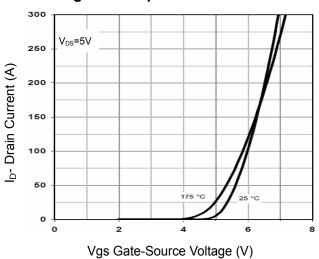


Figure 2 Transfer Characteristics

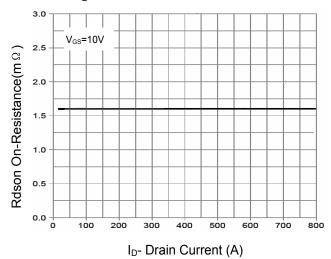


Figure 3 Rdson- Drain Current

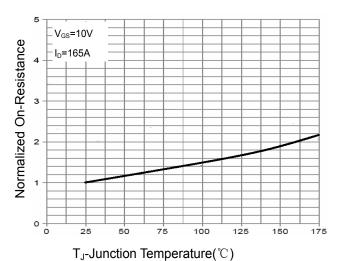


Figure 4 Rdson-Junction Temperature

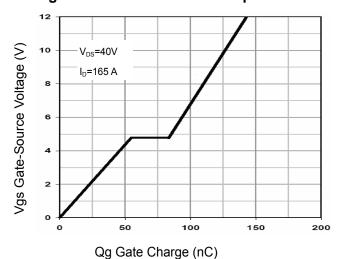


Figure 5 Gate Charge

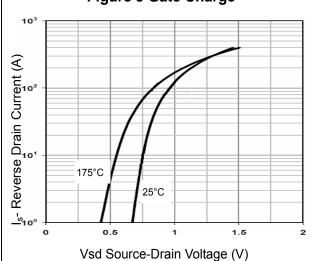


Figure 6 Source- Drain Diode Forward



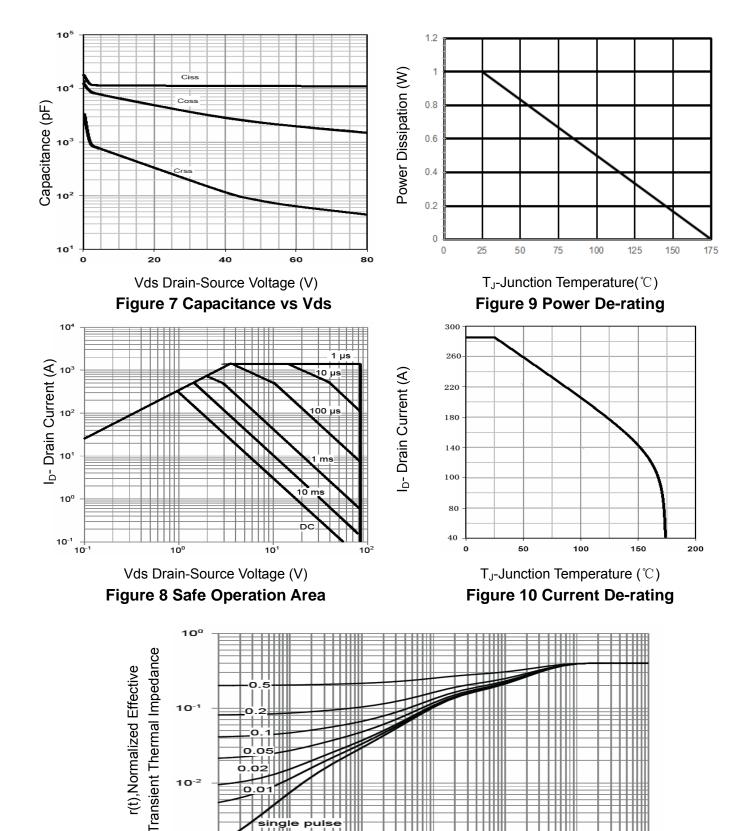
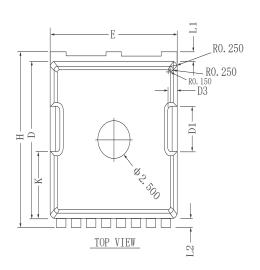


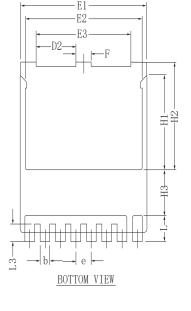
Figure 11 Normalized Maximum Transient Thermal Impedance

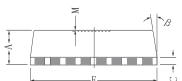
Square Wave Pluse Duration(sec)



•Dimensions (TOLL)

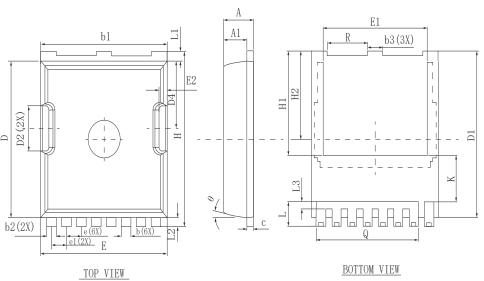




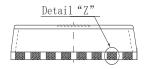


Symbols	Millimeters			
3y110018	MIN.	NOM.	MAX.	
A	2.20	2.30	2.40	
b	0.65	0.75	0.85	
С		0.508 REF		
D	10. 25	10.40	10. 55	
D1	2.85	3.00	3. 15	
D2	2.95	3. 10	3. 25	
D3	0.75 REF			
Е	9.75	9.90	10.05	
E1	9.65	9.80	9. 95	
E2	8.95	9.10	9. 25	
E3	7. 25	7.40	7. 55	
е		1.20 BSC		
F	1.05	1.20	1.35	
Н	11.55	11.70	11.85	
H1	6.03	6. 18	6.33	
H2	6.85	7.00	7. 15	
Н3		3.00 BSC		
L	1.55	1.70	1.85	
L1	0.55	0.70	0.85	
L2	0.45	0.60	0.75	
L3	1.00	1. 15	1.30	
M		0.08 REF		
β	8°	10°	12°	
K	4. 25	4.40	4. 55	

Millimeters







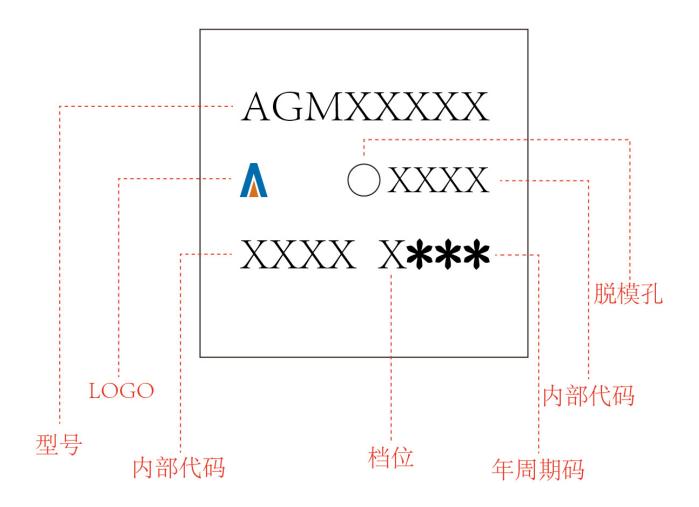


Detail "Z"

		MILL IMPERE		
SYMBOL	MIN	MILLIMETER	MAY	
	MIN.	NOM.	MAX. 2, 400	
A		2. 200 2. 300		
A1	1.700	1.800	1.900	
b	0.600	0.700	0.800	
b1	9.700	9.800	9.900	
b2	0.650	0.750	0.850	
b3	1.100	1. 200	1.300	
С	0.400	0.500	0.600	
D	10.300	10.400	10.500	
D1	11.000	11.100	11.200	
D2	3. 200	3. 300	3.400	
D4	4.470	4. 570	4.670	
Е	9.800	9. 900	10.000	
E1	8.000	8. 100	8. 200	
E2	0.500	0.600	0.700	
е	1.200 BSC			
e1		1.225 BSC		
Н	11.600	11.700	11.800	
H1		6.950 BSC		
Н2		5. 900 BSC		
i	0. 100 REF.			
j	0. 350 REF.			
K	3. 100 REF.			
L	1.550	1.650	1.750	
L1	0.600	0.700	0.800	
L2	0.500	0.600	0.700	
L3	0.400	0.500	0.600	
Q	7. 950 REF.			
R	3.000	3. 100	3. 200	
θ	10° REF.			



TOLL
Marking Instructions:





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